imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Part Number: XZM2MRTNI55W-8

3.2x1.6mm SMD CHIP LED LAMP

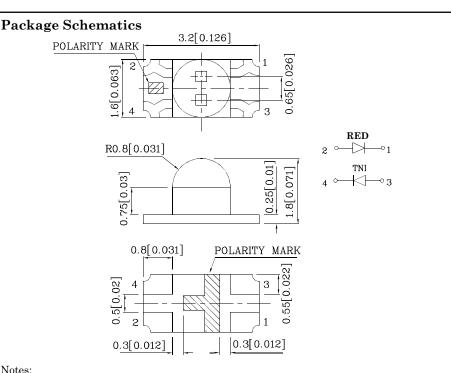
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes: 1. All dimensions are in millimeters (inches).

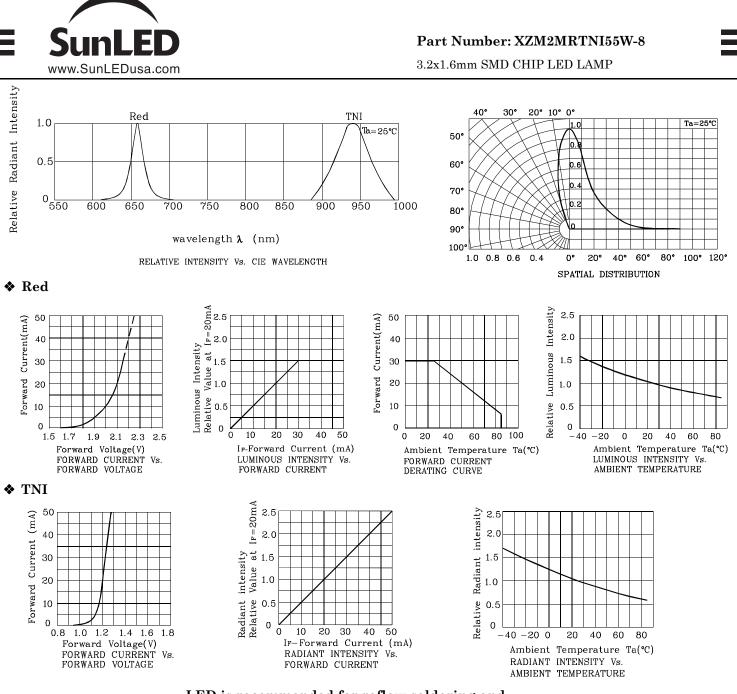
2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ra (T _A =25°C)	atings	Red (AlGaInP)	TNI (GaAs)	Unit		Operating Char (T _A =25°C)	racteristics		Red (AlGaInP)	TNI (GaAs)	Unit
Reverse Voltage	VR	V _R 5 5 V		V		Forward Voltage	(Тур.)	$V_{\rm F}$	2.1	1.2	v
Forward Current	$I_{\rm F}$	30	50	mA		(I _F =20mA)		-			
Forward Current (Peak) 1/10 Duty Cycle		150	1200	mA		Forward Voltage (I _F =20mA)	(Max.)	$V_{\rm F}$	2.5	1.6	V
0.1ms Pulse Width	ifs					Reverse Current (Max.)		I_R	10	10	uA
Power Dissipation	PD	75	80	mW		(V _R =5V)					
Operating Temperature T _A		-40 ~ +85		•C		Wavelength of Peak Emission CIE127-2007* (Typ.)		λP	660*	940*	nm
Storage Temperature	Tst	g -40 ~	+85	C		(I _F =20mA)					
A Relative Humidity betw ESD-protected work area process (Reference JEDE	s to reduce sta	tic build up du	ring assem	bly		Wavelength of Do Emission CIE127 (IF=20mA) Spectral Line Fu At Half-Maximum	7-2007* (Typ.)	λD Δλ	640* 20	- 50	nm
						(I _F =20mA) Capacitance (Typ (V _F =0V, f=1MHz)		С	45	90	pF
Part Number	Emitting Color	Emitting Material	Lens-cole			adiant Intensity Luminous I CIE127-2007* CIE127-2 (Po =mW/sr) (IF=20 @20mA mcd		2007* nA)	CIE127-2007* An		ewing .ngle θ 1/2
					m	in. typ.	min.	typ.			
XZM2MRTNI55W-8	Red	AlGaInP	Watan Ola				500 120*	1295 397*	660*		0.09
	-	GaAs	Water Cle	ear —		2 2.3 .8* 1.3*	-	-	940*		30°

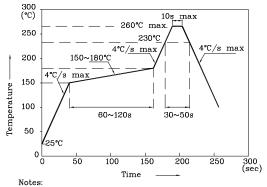
*Luminous/radiant intensity value and wavelength are in accordance with CIE127-2007 standards. Feb 22,2017

XDSB8904 V1-X Layout: Maggie L.



LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



Maximum soldering temperature should not exceed 260°C Recommended reflow temperature: 245°C-260°C 2.

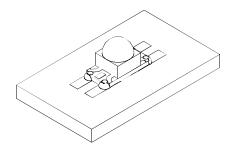
З. Do not put stress to the epoxy resin during

high temperatures conditions

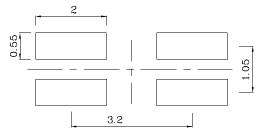


3.2x1.6mm SMD CHIP LED LAMP

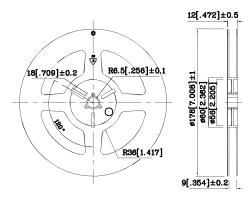
The device has a single mounting surface. The device must be mounted according to the specifications.



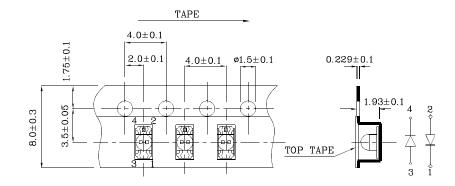
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

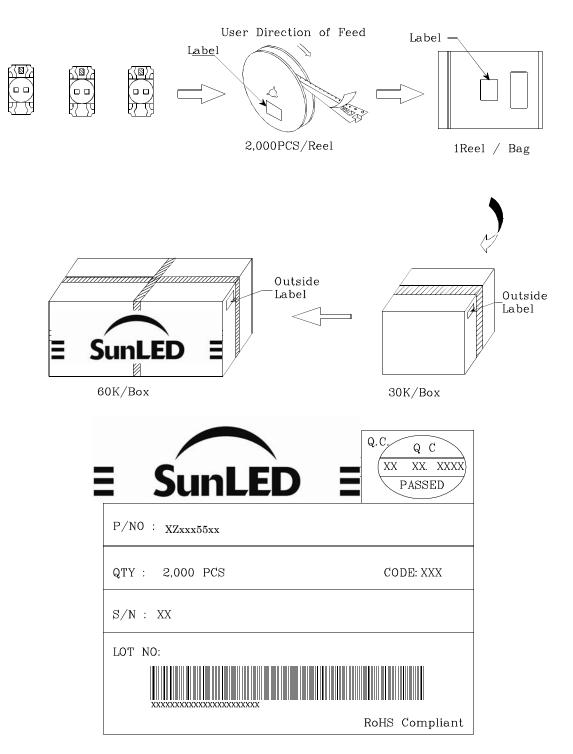
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



3.2x1.6mm SMD CHIP LED LAMP

PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
 - consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

Feb 22,2017

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